an IC Test Company

Corporate Presentation
1. Introduction

2. Business Units

3. Customers

4. Quality

5. Team

6. Logistics

7. USP
Introduction

About Valingro Group
➢ Valingro facilitates, develops & build Enterprises girded by Values
➢ Creating Companies concentrating on Global Competitiveness, Leveraging global Opportunities, Acquiring global capabilities
➢ Philosophy: Business Beyond Profit

About ChipTest Engineering
➢ An associate of Valingro, ChipTest is a Semiconductor Test Company
➢ Established in 2005, ChipTest has 2 BUs : Test Engineering and Wisteria
➢ Over 27 Years of Test Engineering Business Experience
➢ Operations in India, Singapore & Malaysia
➢ Long-Term Value-Added Partnership Business Model

About Wisteria
➢ Wisteria is the Hardware Products & Automation Business Unit of ChipTest
➢ Solutions in Semiconductor, Automotive, Electronics & Process Applications
➢ Integrated team of wide expertise under one roof
Vision

Consistently excel in Semiconductor Test Solutions for global IC & ATE Customers

Mission

Exceed the fast-emerging needs of our Customers by:

- Accelerating time-to-market thru continuous Innovation & high Quality
- Providing unparalleled Service that is Versatile & Cost–effective
Values

1. Business Ethics - defines us as a Company
2. Professionalism - defines us as Individuals
3. Citizenship - defines our Contribution to Society

Corporate Objectives

1. Profit - earnings that enable achieving our other 4 Objectives
2. Client Satisfaction
3. Competence
4. Employee Satisfaction
5. Growth
Business Units

1. Test Services
   a. Products
   b. Tester Platforms
   c. Capabilities
   d. Key Highlights

2. Hardware Products & Automation Solutions - Wisteria

3. Allied Services
1. Test Services

1. Test Plan Derivation
2. Hardware load board and DUT board design & fabrication
3. Test program generation
4. Test program debugging & correlation
5. Product characterization
6. Test time optimization
7. Wafer Sort Verification & Testing
8. Final Device Testing using developed set-up
## 1. Test Services
### Road Map

<table>
<thead>
<tr>
<th>Product / Year</th>
<th>Existing</th>
<th>2020</th>
<th>2021</th>
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<tbody>
<tr>
<td>High-End RF</td>
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<td></td>
<td>✓</td>
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<tr>
<td>High-End Mixed Signal</td>
<td></td>
<td></td>
<td>✓</td>
</tr>
<tr>
<td>High-End Digital</td>
<td></td>
<td>✓</td>
<td></td>
</tr>
<tr>
<td>Power</td>
<td></td>
<td>✓</td>
<td></td>
</tr>
<tr>
<td>Low-End Mixed Signal</td>
<td></td>
<td>✓</td>
<td></td>
</tr>
</tbody>
</table>

*Low-end Mixed Signal & Power Products Capabilities since 1996*
1. Test Services

Products

➢ High Speed Digital Logic & SoC Devices
➢ Automotive products
➢ Clock Drivers, Buffers, PLL & VCO
➢ Power Management Devices
➢ Mixed Signal ASIC Products
➢ Integrated Passive Devices (R, RC & RCD Networks)
➢ Industrial Analog Devices
➢ Audio, Video & Telecom ICs
1. Test Services

Platforms

Existing

➢ Teradyne ETS 364,500,88,800 Mixed Signal Test System
➢ Advantest 93k Pin Scale Digital Test System
➢ Advantest T2000 Test System
➢ Advantest T6573 SoC Test System
➢ ASL 1K Mixed Signal Test System
➢ Teradyne Flex Test System

Proposed

➢ High End Mixed Signal Test System
➢ RF Test System
➢ Memory Test System
<table>
<thead>
<tr>
<th>Feature</th>
<th>Specification</th>
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<tbody>
<tr>
<td>Max I/O channels</td>
<td>64</td>
</tr>
<tr>
<td>Max Vector Rate</td>
<td>133 MVPS</td>
</tr>
<tr>
<td>Max Vector Depth</td>
<td>8 M</td>
</tr>
<tr>
<td>Memory Capture</td>
<td>1 M</td>
</tr>
<tr>
<td>Fail Memory Depth</td>
<td>8 K</td>
</tr>
<tr>
<td>Serial Mode</td>
<td>8 M, 16 M, 32 M</td>
</tr>
<tr>
<td>Driver Level</td>
<td>-1.0 to 7.0 V; 16 Bit</td>
</tr>
<tr>
<td>Current Range</td>
<td>32 mA</td>
</tr>
<tr>
<td>Driver Slew Rate</td>
<td>2 V / nS</td>
</tr>
<tr>
<td>Min. Pulse Width</td>
<td>4 nS</td>
</tr>
<tr>
<td>Formats Supported</td>
<td>NR, RO, RZ, CS, ZS, CPS, CPE, KN, KT</td>
</tr>
<tr>
<td>Receive Bandwidth</td>
<td>&gt; 150 MHz</td>
</tr>
<tr>
<td>Time Sets</td>
<td>4 Unidirectional Per Pin</td>
</tr>
<tr>
<td>Timing Resolution</td>
<td>&lt; 100 pS</td>
</tr>
<tr>
<td>Skew</td>
<td>&lt; 250 pS</td>
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</table>
## 1. Test Services
### Teradyne ETS 364 (Contd...)

<table>
<thead>
<tr>
<th>Parameter</th>
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<th>Range</th>
<th>Channels</th>
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<tbody>
<tr>
<td>Voltage Force</td>
<td>16 Bit</td>
<td>± 10, 30 V</td>
<td>17</td>
</tr>
<tr>
<td></td>
<td>18 Bit</td>
<td>± 100 V</td>
<td>1</td>
</tr>
<tr>
<td></td>
<td>18 Bit</td>
<td>± 10, 30, 100 V</td>
<td>4</td>
</tr>
<tr>
<td>Current Force</td>
<td>16 Bit</td>
<td>± 10, 100 uA; ± 1, 10, 100 mA</td>
<td>17</td>
</tr>
<tr>
<td></td>
<td></td>
<td>± 1, 2, 20, 200 uA; ± 2, 20, 200 mA; ± 1, 2, 40 A</td>
<td>2</td>
</tr>
<tr>
<td></td>
<td>18 Bit</td>
<td>± 1, 2, 10, 20, 100, 200 uA; ± 1, 2, 10, 20, 100, 200, 500 mA; ± 1, 2 A</td>
<td>4</td>
</tr>
<tr>
<td>Voltage Measure</td>
<td>16 Bit</td>
<td>± 10, 30 V</td>
<td>21</td>
</tr>
<tr>
<td></td>
<td>18 Bit</td>
<td>± 100 V</td>
<td>5</td>
</tr>
<tr>
<td></td>
<td>18 Bit</td>
<td>± 0.5, 1, 2, 5, 10, 20, 30, 50, 100, 200 V</td>
<td>4</td>
</tr>
<tr>
<td>Current Measure</td>
<td>16 Bit</td>
<td>± 1, 2, 20, 200 uA; ± 2, 20, 200 mA; ± 1, 2 A</td>
<td>5</td>
</tr>
<tr>
<td></td>
<td></td>
<td>± 500 mA</td>
<td>4</td>
</tr>
<tr>
<td></td>
<td></td>
<td>± 40 A</td>
<td>2</td>
</tr>
<tr>
<td></td>
<td></td>
<td>± 10, 100 uA; ± 1, 10, 100 mA; ± 1, 2 A</td>
<td>21</td>
</tr>
</tbody>
</table>
1. Test Services
ETS 364 Capabilities

➢ High Voltage & Current Handling: ± 100V, 40 A
➢ Per Pin Digital Architecture with On-Board DSP
➢ Time Measurement Unit with 5 pS Resolution
➢ High Precision Voltage Digitizer: 4 uV Resolution, 4 MHz BW
➢ High Speed Digitizer: 4 GSPS, 1 GHz BW
➢ Programmable Low Jitter Clock Source: 10 MHz to 1 GHz
➢ Programmable V/I Waveform Generator in each Analog Channel
➢ Robust math & data analysis Library
➢ True Parallel Multi-site Testing possible
1. Test Services – Case Studies

- Audio / Video Decoders
- Notebook DDR Power Controllers
- White LED Charge Pump Drivers
- Li/ Ion Battery Chargers
- Hearing Aid DSP Controller
- MEMS Clock & EMI Clock Synthesizers
- Digital Multiphase Controllers
- Power Interface Switch Products
- Dynamic Beam Steering Controller
- RF LDO, FET, Laser Diode Drivers and much more
1. Test Services
Key Highlights - ETS

➢ Extent knowledge in handling HPU, MPU, SPU100, APU12, QMS and DPU16

➢ Expertise execution of AWG, DGT and time measurement using pattern sequencer

➢ Expertise communicating external equipment's like VI meter, Network analyzer,

➢ Hands on in Handling pico-amp module to measure the nano and pico amps.

➢ Worked on various trimming tests (Voltage, current and oscillator), ADC and DAC

➢ Trimming and OTP done using registers (SPI & I2C protocols) and Physical fuses.

➢ Used APU12 as APU10, DPU16 as DPU8 in emulation mode

➢ Good knowledge on resource & test time optimization for multi Site solutions

➢ Worked on various ETS platforms ETS88, ETS200, ETS364, ETS500 and ETS800
1. Test Services

Key Highlights - 93K

- 93K SW version from 5.X to 8.X
- Extent knowledge in handling resources PS800, PS1600 and AVI64
- Protocol Aware for script handling
- Firmware command usage in FW task
- Test method development for Digital and Analog Resources
- Vector conversion from evcd, wgl, stil to V93k binaries
- Experience in Handling the X mode vector
- Experience in SOC TML & TP360 tools.
- Experience in handling the DPS and Digital resources
- Digital Debug Tools: Shmoo, Pinmargin, Error Map & Timing diagram
1. Test Services

Key Highlights – T2K

- Expertise in converting automotive products from legacy Systems to T2K
- Worked on Digital inputs, MSS interface, Safety switch, Clamp & Temperature check modules of Automatic parking and braking IC
- Worked on SPI parameters, DCS, SyncPulse, JVT modules of Air Bag IC
- Performed VI spike check, plausibility check, GRR stability, 1000X loop, Bin flip analysis
- Extent use of Block Diagram, System viewer, Wave & Shmoo, Statistical analysis tools
- Low Rdson measurement of 50mohms with accuracy < 5mohms at WLCSP
- Measuring AC delay between 2 resource (MDMA/MMXH) using Module trigger
In depth knowhow of semiconductor operations (Sort & Final test) with rounded skill sets on data mining technologies.

Actionable insights from the massive amount of Data generated in semiconductor manufacturing operations and drive time-sensitive decisions that significantly optimize Yield, Quality and Productivity.

Data derived from major foundry and OSATs can be intelligently worked upon to measurably improve Yield, Throughput, Tester Efficiency, Quality and RMA prevention.

Provide customized reports required to Top Management on a daily basis.

Experience in handling various industrial standard software like Optimal Tool, Data Power, Sedana, Galaxy etc.
2. Hardware Products - PCB

- Design for High Speed Digital & Precision Analog needs
- Schematics Design – Cadence CAPTURE, Mentor PADS LOGIC & ALTIUM
- Board Layout Design - ALLEGRO, ALTIUM and PADS Layout
- Implementation of High-Speed Layout techniques
- ATE load board design techniques.
- BGA Routing Techniques.
- Blind and buried Via’s Implementation
- Final QC and CAM Support.
- Floor Planning, Net rules, Layer Stack-up planning & Placement constrains.
- Done for ATE Platforms like Verigy, Advantest, Teradyne, LTX-Credence
- Global Route Environment & Quick turnaround time
2. Hardware Products - PCB

- Layer count: 2 to 56 layers
- Minimum trace width / spacing: 2.5 mils
- Minimum Platted hole and PAD size: 4/12 mils.
- Board size: 22.5" x 28.5" max
- Board thickness: 0.016" - 0.280"
- Aspect ratio: 34:1
- Outline tolerance: + 5 mils min
- Copper thickness: Upto 4 oz
- Impedance control tolerance limit: + 3 %
2. Hardware Products
Gravity PTB Handler

- Hot & Ambient Testing with Option for Cold
- Various Packages with Conversion kit in each Family
- User Friendly Touch Screen Interface
- Real Time Product & Error Monitoring Display
- Bench top & Production Test Applications
- Hard Dock & Soft Dock Mechanisms
- Proven Poke Yoke Features
- Economical & Lower Foot print
- Accelerated Return of Investment
2. Hardware Products
Pick and Place Tri-temp Handler

- Automatic Pick & Place System with TCU Plunge
- Improved Efficiency with Precise Device Insertion
- Variety of Device sizes with same Base
- Easy Conversion Capability for different packages
- Fast and User Friendly Touch Screen operations
- Real time Error Monitoring / Device Status display
- Remote System Operation & Monitoring
- Simple, Reliable and Easy to maintain
- Economical Low Foot print Areas Space
- Cost Effective Production Test possible
2. Hardware Products

Universal Test Head Manipulator

- Modular Low-Cost Reliable design
- Optimum Footprint Area – 1410 x 1220 mm (56 x 48 inch)
- Gravity Feed & Pick/Place Handler Interface
- Overhead Wafer Sort Prober Interface
- Easy positioning with Linear movements
2. Automation Solutions

- Pick & Place Solutions for Industrial Applications
- Poke yoke systems to avoid manual errors
- Auto Liquid dispensing Systems
- Inline Automated Screw Feeding, Mounting & Inspection Systems
- OEE report dashboard of Inline equipment’s data
- Automated Gang Flash programmer for Set Top Box (STB) application
- PLCC Based System Automation to PIC/PC Based System
- Design for High Speed Digital & Precision Analog PCB needs
- Line Follower Trolleys for Product Movement
- Auto Loading / Unloading Feature for Manual Equipment’s
- Automation Hardware System Design, Development & Validation
- Automation Software Development for Control & Interface
3. Allied Services

- Onsite Test Engineering Support
- Associated partners for the following:
  - Prototype Samples Packaging
  - Surface Mount Package – Production Assembly
  - Lead Scan / Tape & Reel Finish Process
  - New Product / Package Qualification
  - Long Term Reliability tests - HTOL, HAST, TMCL, Autoclave, etc.
  - External & Internal Failure Analysis – X-ray & Decap
  - Other Failure Analysis like ESD, Latch-up & CSAM
<table>
<thead>
<tr>
<th>SI #</th>
<th>Reliability Test Name</th>
<th>Jedec Ref#</th>
<th>Test Conditions</th>
<th>Test duration</th>
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<tbody>
<tr>
<td>1</td>
<td>Initial CSAM inspection</td>
<td>J-STD-020C</td>
<td>-</td>
<td>-</td>
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<tr>
<td></td>
<td>Pre-conditioning test</td>
<td></td>
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</tr>
<tr>
<td></td>
<td>Temperature Cycling</td>
<td>JESD 22 A113-E</td>
<td>-40°C to +60°C</td>
<td>5 Cycles</td>
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<tr>
<td></td>
<td>Stabilization Bake</td>
<td></td>
<td>125°C</td>
<td>24 Hrs</td>
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<tr>
<td></td>
<td>Moisture Soak</td>
<td></td>
<td>85°C / 85% Rh</td>
<td>168 Hrs</td>
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<tr>
<td></td>
<td>Solder Reflow</td>
<td></td>
<td>260°C</td>
<td>3 Cycles</td>
</tr>
<tr>
<td></td>
<td>Final CSAM inspection</td>
<td>J-STD-020C</td>
<td>-</td>
<td>-</td>
</tr>
<tr>
<td>2</td>
<td>High Temperature Storage test</td>
<td>JESD 22 A103-C</td>
<td>150°C</td>
<td>1000 Hours</td>
</tr>
<tr>
<td>3</td>
<td>High Temperature Operating Life Test</td>
<td>JESD 22 A108-C</td>
<td>125°C, Max Vdd</td>
<td>1000 Hours</td>
</tr>
<tr>
<td>4</td>
<td>HAST Test</td>
<td>JESD 22 A110-C</td>
<td>130°C, 85% RH</td>
<td>96 Hours</td>
</tr>
<tr>
<td>5</td>
<td>Pressure Pot Test</td>
<td>JESD 22 A102-C</td>
<td>121°C, 100% Rh</td>
<td>168 Hours</td>
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<tr>
<td>6</td>
<td>Temperature Cycling test</td>
<td>JESD 22 A104-C</td>
<td>-60°C to +150°C</td>
<td>1000 Cycles</td>
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<td>7</td>
<td>ESD Test</td>
<td>JESD 22 A114-D</td>
<td>-</td>
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<tr>
<td>8</td>
<td>Latch Up Test</td>
<td>JESD 22 78A</td>
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### 3. Allied Services
#### FA Facilities

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<tr>
<th>SL #</th>
<th>Test Description</th>
<th>Manufacturer</th>
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<tbody>
<tr>
<td>1</td>
<td>Optical Inspection at 1000X</td>
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</tr>
<tr>
<td>2</td>
<td>X-ray Inspection for internal assembly abnormalities</td>
<td>Phoenix, Germany</td>
</tr>
<tr>
<td>3</td>
<td>Scanning Acoustic Microscopic Inspection (Through Scan, C-scan, B-scan &amp; A-scan)</td>
<td>Sonix, USA</td>
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<tr>
<td>4</td>
<td>Chemical Decapping</td>
<td>Nisene, USA</td>
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<tr>
<td>5</td>
<td>Cross Sectional analysis</td>
<td>Buehler, USA</td>
</tr>
<tr>
<td>6</td>
<td>Die Shear Test</td>
<td>HMP, USA</td>
</tr>
<tr>
<td>7</td>
<td>Ball Shear Test</td>
<td>Royce, USA</td>
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<tr>
<td>8</td>
<td>Wire Pull Test</td>
<td>HMP, USA</td>
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### 3. Allied Services

#### Reliability Facilities

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<th>SI #</th>
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<tbody>
<tr>
<td>1</td>
<td>Burn-in</td>
<td>Blue-M, USA</td>
</tr>
<tr>
<td>2</td>
<td>Temperature &amp; Humidity</td>
<td>Blue-M, USA</td>
</tr>
<tr>
<td>3</td>
<td>Temperature Cycler</td>
<td>Blue-M, USA</td>
</tr>
<tr>
<td>4</td>
<td>HAST</td>
<td>Hirayama, Japan</td>
</tr>
<tr>
<td>5</td>
<td>Dry Heat (Class 100) Oven</td>
<td>Labline, USA</td>
</tr>
<tr>
<td>6</td>
<td>Autoclave</td>
<td>Hirayama, Japan</td>
</tr>
<tr>
<td>7</td>
<td>Steam Ager</td>
<td>Mountain Gate, Singapore</td>
</tr>
<tr>
<td>8</td>
<td>Solder Pot</td>
<td>HMP, USA</td>
</tr>
<tr>
<td>9</td>
<td>Lead Integrity Tester</td>
<td>HMP, USA</td>
</tr>
<tr>
<td>10</td>
<td>Reflow Oven</td>
<td>Heller, USA</td>
</tr>
</tbody>
</table>
Quality Policy

“To consistently excel in Semiconductor Test Software and Hardware Solutions and exceed the fast emerging needs of our Customers through continuous innovation, high quality, accelerated, versatile & cost–effective services, along with increasing value addition to all stakeholders”
➢ Quality Controlled Process flow approach
➢ Archival of Process records and Quality data
➢ Closely monitored Corrective Action Systems
➢ Well defined Process Flow documents & Check-lists
➢ Setting & Monitoring of Key Performance Indices
➢ Project Scheduling & Milestone Tracking
➢ Systems for Continuous Process Improvement
➢ Customer specific Qualification Process
Quality Certifications

CERTIFICATE

The Certification Body of TÜV SÜD South Asia Private Limited certifies that

ChipTest Engineering Limited
16, Zakaria Colony, 1st street, Choolaimedu,
Chennai - 600 094, INDIA

has implemented a Quality Management System in accordance with ISO 9001:2015
For Scope of

Provision of Semiconductor Test Services and Associated Hardware Products

The certificate is valid from 2019-06-30 until 2021-06-29

Subject to successful completion of annual periodic audits
Further certifications regarding the scope of this certificate may be obtained by contacting the certification body.

Certificate Registration No. 99100-4659
Date of Initial certification: 2013-01-13

ISO 9001:2015 Certification
Customers

- Integrated Device Manufacturers
- Fabless Product Design Companies
- Start-up, ATE & Subcontracting Companies
- Equipment Manufacturing Companies
Customers (Contd…)

➢ Global Semiconductor Customer Base
➢ Markets Served – America, Asia Pacific & India
➢ Markets Explored – Europe, Japan
➢ Applications – Mobile, Computing, Automotive & Consumer
➢ Customer Specific Dedicated Teams – Offshore & Onsite
➢ Inbuilt Long Term Partnership Model
Professional Team

- Well Experienced Leadership
- Talented Test Engineers
- Qualified & Skilled Technicians
- Proficiency in Communicating in English
- Low Direct Labor Cost
- Ready availability of Engineering Resources for expansion
For most people, the idea of Social Service is donating money to a social organization - perhaps an old-age home or an orphanage or similar. This however is the easy part. The difficult part is volunteering one's time to improve society.

When can we make a contribution to society

- **During Phase 1** of our lifetime, perhaps up to the age of 35, we are so focused on building our careers, starting our families & establishing a name for ourselves.

- **During Phase 2**, perhaps from age of 35 thru 65, we are the most active in our work, working as a team, being able to significantly contribute to Economic Development.

- **During Phase 3** perhaps from age 65 onwards, we are most able to contribute our time on an increased basis to social causes.
S-E-C at ChipTest is all about how we can contribute socially during Phase 2 itself while also handling Economic Development.

Towards this, there are 3 areas that each of us can assist by making these a part of our day to day approach:

1. Following discipline in any and everything we do
2. Providing a helping hand to people around us in any way we possibly can
3. Showing the right path forward to people around us

S-E-C in ChipTest is primarily done by One-to-One Mentoring as each person encourages & motivates the other, towards a more purposeful & effective lifestyle.
AlphaOmega Institute for Semiconductors

➢ Unique one for Semiconductor Training

➢ 6 months PG Diploma Course in IC Assembly & Test

➢ Incumbents are the Engineering graduates

➢ Practical Online Training with State of the Art Equipments

➢ Dissertation in Tester Software & Hardware in ATE

➢ Trained Professionals readily available for expansion
Logistics

- Green Channel Status for Imports & Exports
- Zero Duty
- No Open Inspection
- Clearance within 6 Working Hrs
- Drop ship Facility to end Customers
- Proximity to Sea & Air Ports with efficient Cargo Handling
Logistics (Contd…)

- Easy Equipment Consignment In & Out of our Facility
- Daily Flights to US, Europe & Asia Pacific Destinations
ChipTest - USP

- 27+ Years of Experience in Test Engineering & Operations Management
- Skilled Talent in Advantest & Teradyne ATE, Production Handlers & Probers
- Rich Expertise in recent Technology SoC & Mixed Signal Products
- Yield Monitoring, Data Mining & Statistical Process Analysis Capabilities
- Turnkey support: New Product Development till post Manufacturing Release
- Hardware Design & Development: Load Boards, Sockets, Probe Cards, Stiffeners
- Indigenously developed, Globally commercialized Handlers & Automated Solutions
- Well documented, Customer specific Process Driven Approach
- Focus on Continuous Efficiency improvements & Test Cost Optimization
- Dedicated, Scalable, Flexible Onsite & Offshore Customer Support Teams
- Transparent, Ethical, Adaptive and Value added Service Support
- Trustworthy, Long Term Partner for Engineering Support
- Global Presence: India, Singapore & Malaysia and exploring USA & Europe
Contact

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Please visit our Website for

➢ Resource, Capability Details
➢ Projects Case Study Details
➢ ChipTest’s News and Events
➢ Electronic Hardware Industry News
➢ Global Semiconductor Industry News